

# Global G1 – Triple cut form factor

2FF, 3FF, 4FF

## Product overview

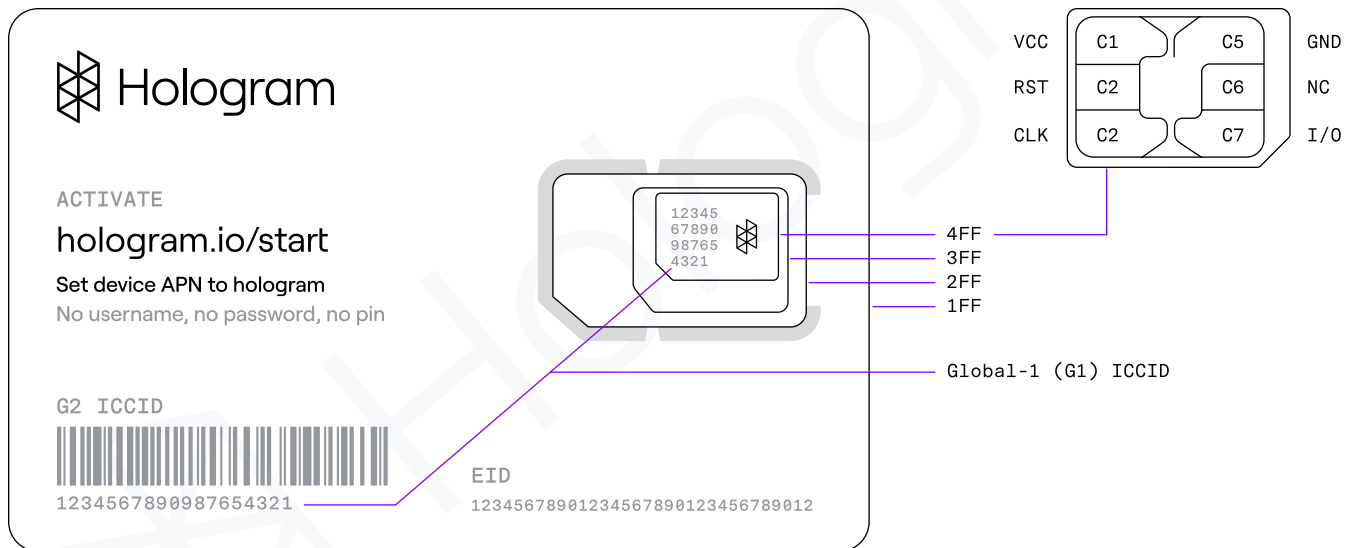
A secure, device-agnostic IoT SIM card for global deployments built for M2M data, with easy activation, transparent pricing, and developer-friendly tools. Hologram's Hyper SIMs are eUICC compliant and the Hyper platform remotely updates coverage over-the-air by adding or removing profiles, without requiring you to swap the SIM in your device.

## Network availability

Works globally with Hologram's 2G through 4G (LTE) network including LTE-M and NB-IoT where coverage is available.

More information: <https://www.hologram.io/pricing/coverage>

## Mechanical specifications



## Part numbers

G1  
G1-10  
G1-100  
G1-1000  
G1-IG  
G1-IG-10  
G1-IG-100  
G1-IG-1000

## Past part numbers

GL1  
GL1-10  
GL1-100  
GL1-1000  
SIM-E-TRI-GL  
SIM-E-TRI-GL-10  
SIM-E-TRI-GL-100  
SIM-E-TRI-GL-1000

## SIM card physical characteristics

### Size

Form Factor	Size	Dimensions (mm)
1FF	Full-Size	85.5 × 53.98 × 0.71
2FF	Mini-SIM	25 × 15 × 0.71
3FF	Micro-SIM	15 × 12 × 0.71
4FF	Nano-SIM	12.3 × 8.8 × 0.71

### Pin definitions

Pin	Function	Description
C1	VCC	Input Voltage
C2	RST	Reset
C3	CLK	Clock
C5	GND	Ground
C6	NC	No Connect
C7	I/O	Input/Output

## Hardware specifications

### Chip type

	Standard grade	Industrial grade
Supplier	Samsung	Samsung
Chip Code	S3FW9FG	S3FW9FJM

### Hardware characteristics

	Standard grade	Industrial grade
Operational Temperature	-25°C to +85°C	-40°C to 105°C
Data Retention	25 years @ 25°C	15 years @ 85°C
Write Endurance	>500K read/write cycles @ 25°C (OS enhanced)	>500K read/write cycles @ 85°C
Remaining Available Memory (NVM)	340 KB	704 KB
Memory (SRAM)	10 KB	20 KB








### Electrical

	Standard Grade	Industrial Grade
Operating Voltage	1.6V, 3V, and 5V	1.62V to 5.5V

### AC electrical parameters standards

ETSI 3GPP TS 102 221 Class A, B, C – UICC Terminal Interface Physical & Logical Characteristics  
ETSI TS 102 671 v9.1.0 – M2M Physical and Logical Characteristics  
ISO/IEC 7816-3 standard for Cards with Contacts – Electrical interface and transmission protocols

## Compliance

Chip	 Common Criteria	EAL: PP-0084/35
OS		SGP:11 RSP v3.1; SGP:14 eUICC PKI v1.1; SGP:02 v3.2 ; SGP:05 eUICC PP-0089
	 TRUSTED CONNECTIVITY ALLIANCE	SIMalliance eUICC Profile Package Interoperable Format Technical Specification v2.1
		Card Specification Version 2.1.1
Software		Java Card 3 Platform, Classic Edition version 3.0.4
		Release 8
Remote SIM provisioning		SGP:01 RSP v1.1 ; SGP:11 RSP v3.1 & 3.2; SGP:14 eUICC PKI v1.1 ; SAS-SM
Supplier's Declaration of Conformity		<p>Manufactured according to the following standards:</p> <ul style="list-style-type: none"> <li>• RoHS Directive 2011/65/EU</li> <li>• Reach certification</li> <li>• GSMA SAS-UP</li> <li>• ISO 9001:2015</li> <li>• ISO 27001</li> <li>• ISO 18001</li> <li>• ISO 17025</li> </ul>